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(54) Title (EN): HERMETIC PACKAGING OF ELECTRONIC COMPONENTS

(54) Title (FR): BOÎTIER HERMÉTIQUE POUR COMPOSANTS ÉLECTRONIQUES

(57) Abstract:

(EN): The present invention relates to the field of electronic devices, in particular implantable electronic devices, e.g. for bio-medical applications, and more particularly, to hermetically packaged electronic devices for bio-medical in vivo applications and packaging methods for such electronic devices.

(FR): La présente invention concerne le domaine des dispositifs électroniques, en particulier des dispositifs électroniques implantables, par exemple pour des applications biomédicales, et plus particulièrement, des dispositifs électroniques encapsulés hermétiquement pour des applications biomédicales in vivo et des procédés d'encapsulation pour de tels dispositifs électroniques.

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